

ABSTRACT

An electrical element mounting package includes a plate-like substrate (10) and at least one base (11) that protrudes from a front surface (10a) of the substrate (10) and has a mounting surface (11a) on which an electrical element is mounted, wherein the substrate (10) and the base (11) are made of ceramics integrally. The electrical element mounting package includes an element terminal (12a) that is provided on the mounting surface (11a) of the base (11), a side conductor (13) that is provided on a side surface (11b) of the base (11) and extends in a thickness direction of the base (11), and a substrate-side via conductor (15a) that is provided inside the substrate (10) and extends in a thickness direction of the substrate (10), wherein the element terminal (12a), the side conductor (13), and the substrate-side via conductor (15a) are connected to one another.

FIG. 1A